Lesson Learned in MOSFET Burn-out Test

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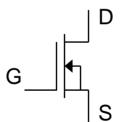
- 1 The usual evaluation process
- 2 The results & the surprise
- 3 How to explain . . . !
- 4 Lesson learned, The message
- 5 A proposal for a reliability calculation method
- 6 Conclusions





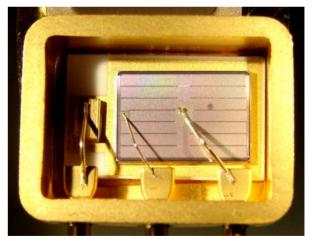
Burn-out :

It is not : *noun -* Burn-out of worker, staff : overwork, exhaustion - Aerospace : final phase of combustion



But for our community, It is :

SEB – Single Event Burn-out



The Power MOSFET destruction by ONE ion







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Burn-out: A destructive event ! 100 ┿ 200 V Heavy ions beam DC $Flux = n/s \cdot cm^2$





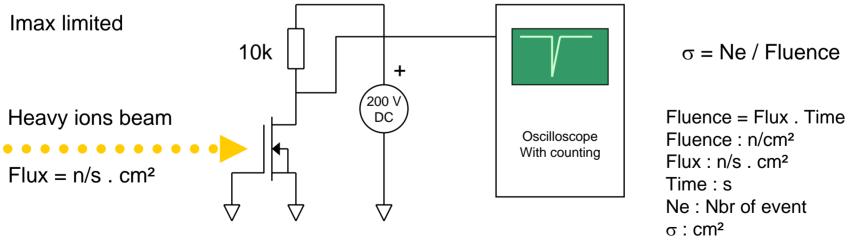


Test process objective :

search for the LET threshold of the SEB for a given Vds

Ions beam is perpendicular to the surface (worst-case)

■ We detect and count the SEB . . .







With the LET threshold, by assuming that

The solid angle of sensitivity is a cone 60° open

 (ref: D.L. Oberg and all – First Destructive Measurement of Power MOSFET SEB Cross-Section – IEEE Vol NS-34, N° 6, December 1987 PP 1736 – Fig 11)



We can compute the reliability . . .

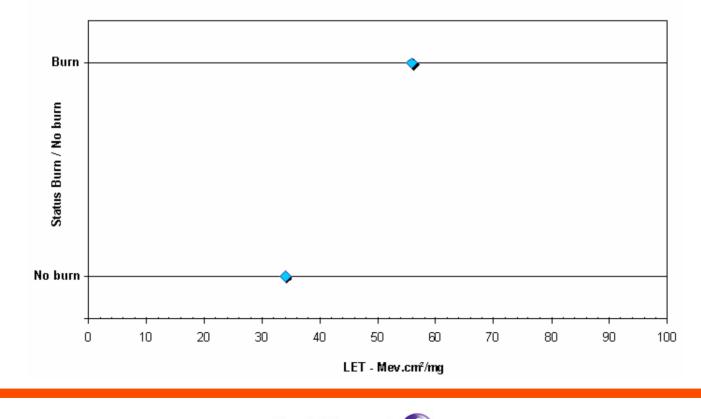
 $FIT = Flux(@LET_{Th}) \times \sigma \times 6.048 \times 10^8$

FIT : 1 failure / 10⁹ h = 1 failure / 114 077 years
Flux : Flux at the LET_{th} in ion/m².sr.s





A first campaign done at HIF facility . . .

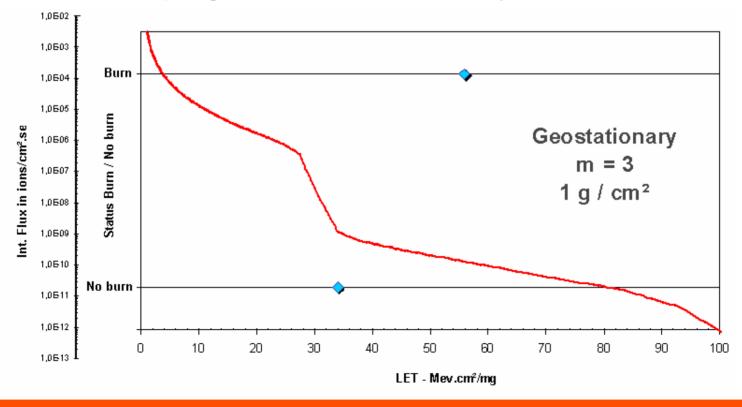








A first campaign done at HIF facility . . .



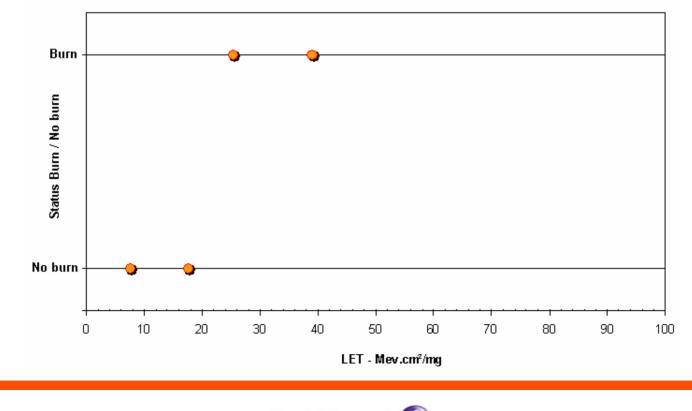
January 2007







A second campaign done at TAMU facility . . .

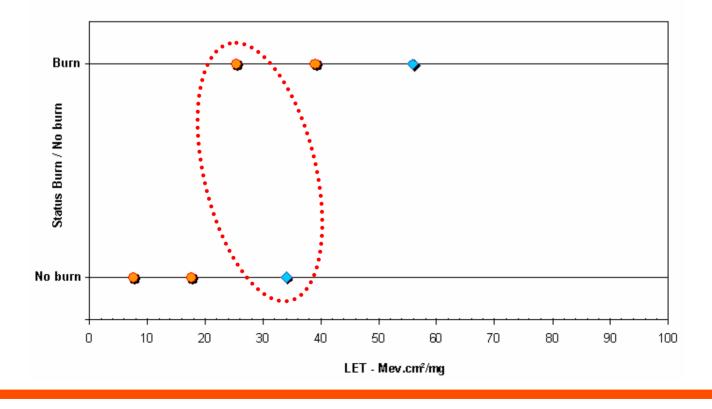






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The global results seems illogical !







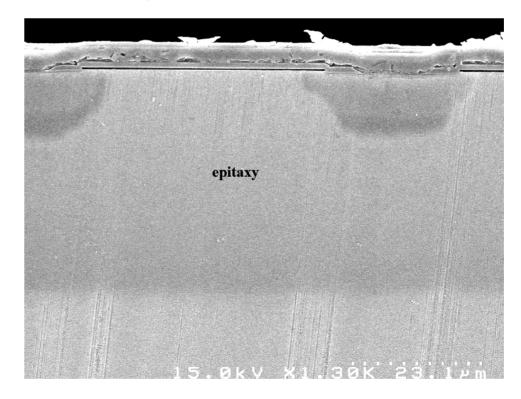


The key : The active zone is deep !

5 µm for SiO2 and Al

39 µm for epitaxial Si (n doped)

Then let consider the LET evolution within the active zone as previously published in IEEE TNS

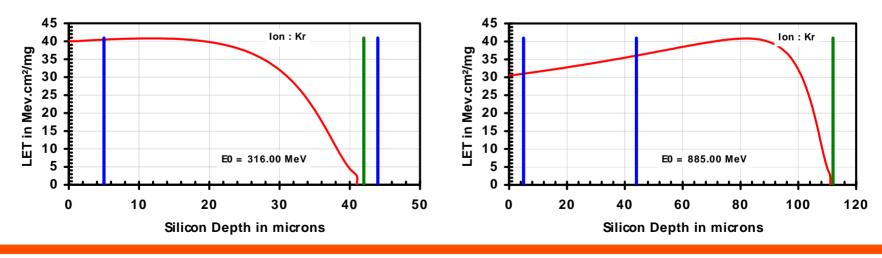






Calculation of the charge deposited

- Cyclotron : UCL vs TAMU
- Energy : Kr 316 MeV vs Kr 885 MeV
- LET : 40 MeV.cm²/mg vs 30.6 MeV.cm²/mg
- Deposited charge : 12.0 pC vs 13.1 pC

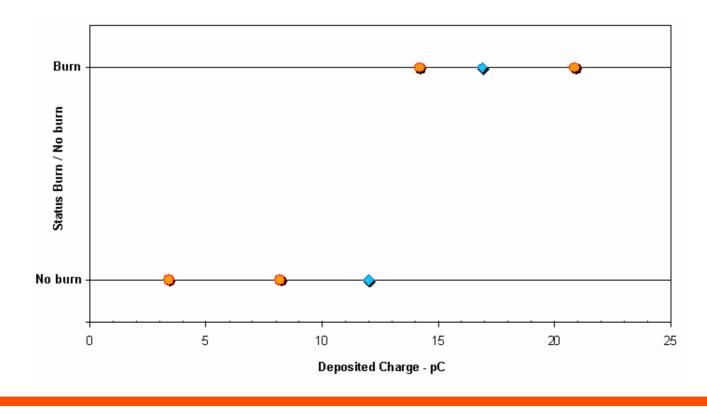








Everything is now logical !

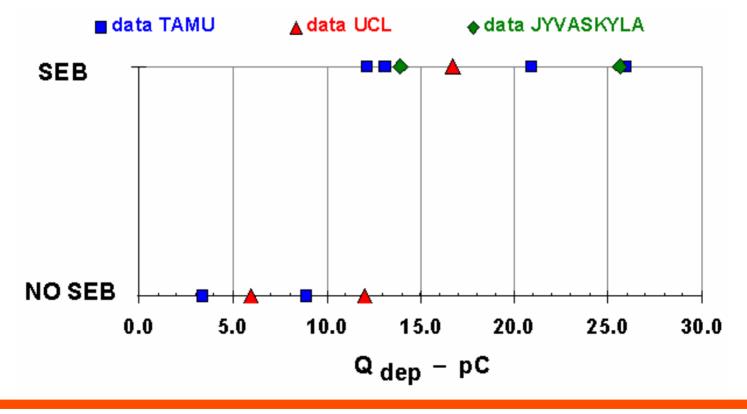








And confirmation with a third machine and an other device







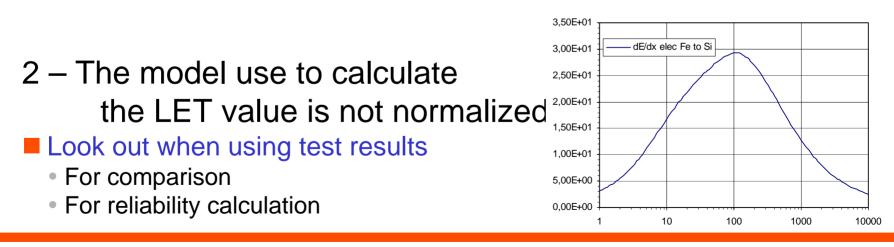
Lesson Learned – The Message

1 – The LET provide by cyclotron administrator are given at the device surface

As the particle penetrate the silicon, the energy droop and the LET change

Look out for device with deep active zone

Power MOSFETs and medium voltage analogue integrated circuits







Proposal for Reliability Calculation

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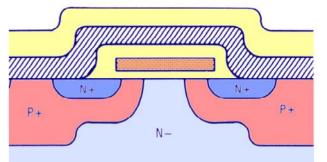


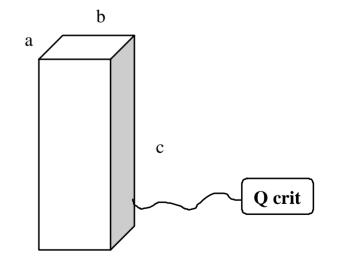
The MOSFET is made up elementary cells

- 42000 cells for IRF360
- We can measure cross-section
 - Use of non-destructive method

The sensitive volume is parallelepipedal

- Dimension 5 μm x 5 μm x 39 μm for IRF360
- The collected charges = deposited charge

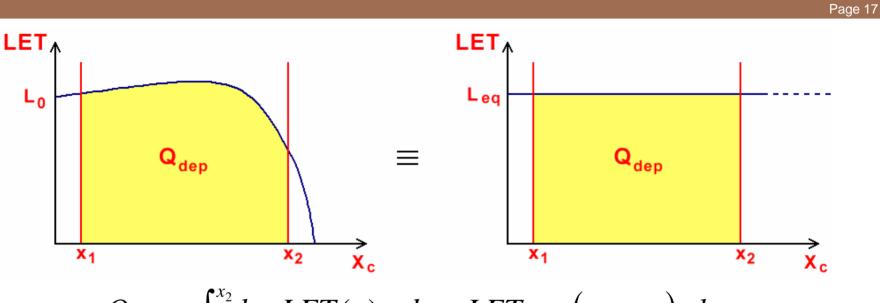








Proposal for Reliability Calculation



$$Q_{DEP} = \int_{x_1}^{x_2} k * LET(x) * dx = LET_{EQ} * (x_2 - x_1) * k$$

Then, we can use classical tools for reliability calculation . .

CRÈME – OMERE (same hypothesis)

... for devices with deep active zone





Proposal for Reliability Calculation

We agree that . . .

- It is a raw / pragmatic / industrial approach !
- This method need to be refined / validated / tested
- ... that is why ...
- We have initiated a thesis in partnership with IXL Bordeaux / CNES / AAS
- It is part of CNES R&D Study 2006/2007







Conclusions

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This practical experience show :

Basically, LET is not the key parameter for SEE assessment, it is the collected charge or more practically, the deposited charge

For devices with deep active zone, the use of LET as a key parameter can end to a failure ! we have to consider the range

As the LET calculation is not normalized, check the model used by the cyclotron administrator and the reliability calculation tool

A method, based on deposited charge, for reliability calculation is proposed





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